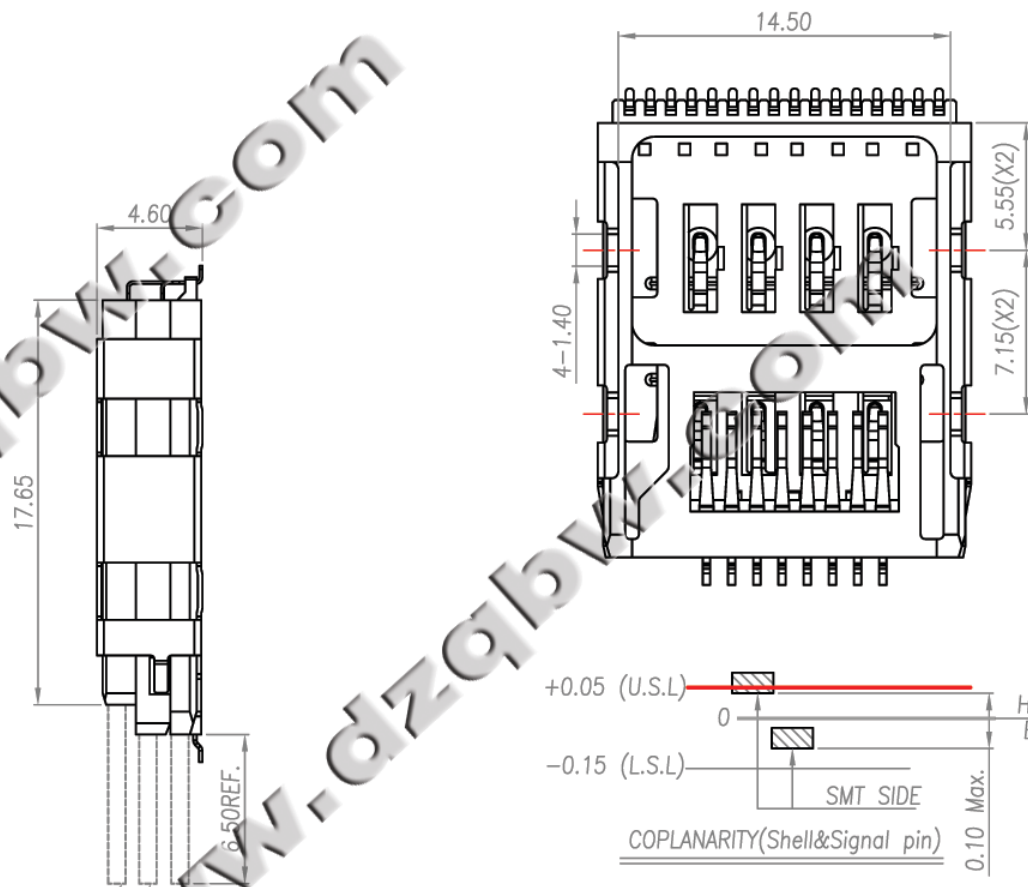
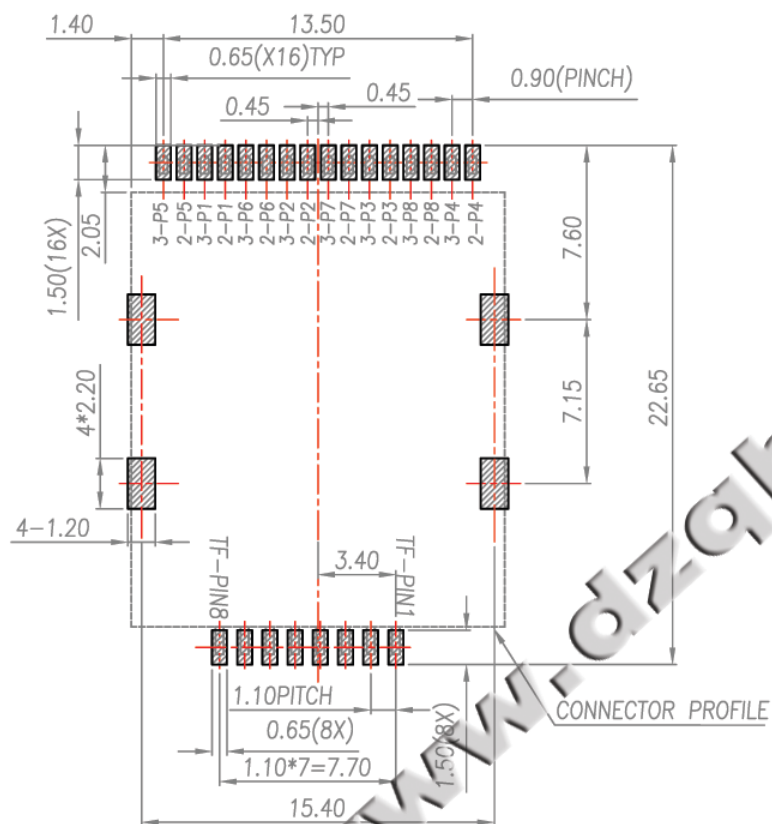




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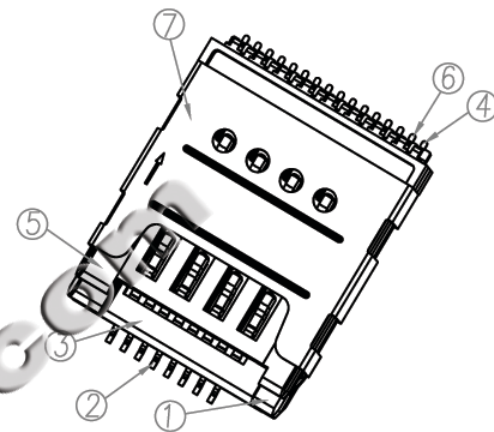
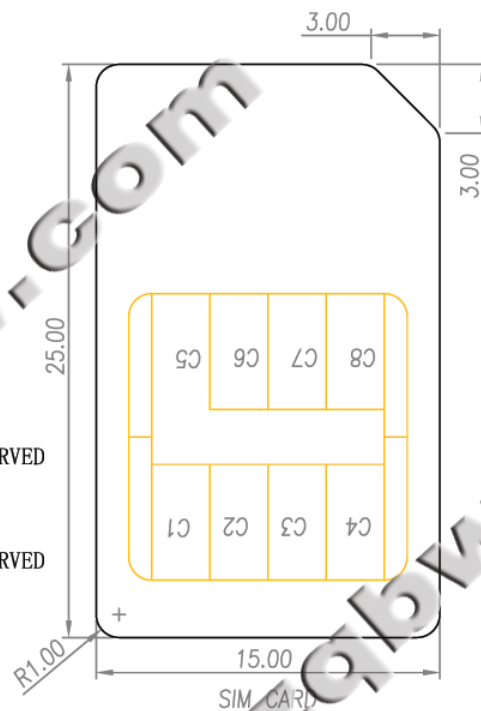
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*	DRAWN BY : 吴迪	DATE : 2012-02-11	PART NAME: TF+2SIM卡座三层卡座	
	CHECKED BY: 马跃	DATE : 2012-02-11	PART NO.	HYC01-3IN124-460
			MOLD NO.	
	 UNIT: mm [inch]	APPROVED BY: 邱国夷	DATE : 2012-02-11	DRAW NO:
SHEET NO.				1 OF 2
SCALE:1:1	SIZE: A4			



SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT

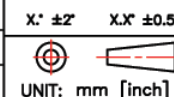
GENERAL TOLERANCE ± 0.05 C1:VCC
C2:RST
C3:CLK
C4:RESERVED
C5:GND
C6:VPP
C7:I/O
C8:RESERVED

TF CARD TERMINAL NO.	PIN NO.
PIN 1	DAT2
PIN 2	CD/DAT3
PIN 3	CMD
PIN 4	VDD1
PIN 5	CLK
PIN 6	VSS
PIN 7	DAT0
PIN 8	DAT1

7	SHELL	1	STAINLESS STEEL/SOLDER TAIL COLD PLATED
6	UPPER CONTACT	8	COPPER ALLOY/CONTACT AREA GOLD PLATED
5	UPPER HOUSING	1	HIGH TEMPERATURE UL 94-V0 BLACK
4	MIDDLE CONTACT	8	COPPER ALLOY/CONTACT AREA GOLD PLATED
3	MIDDLE HOUSING	1	HIGH TEMPERATURE UL 94-V0 BLACK
2	UNDER CONTACT	8	COPPER ALLOY/CONTACT AREA GOLD PLATED
1	UNDER HOUSING	1	HIGH TEMPERATURE UL 94-V0 BLACK
ITEM	NAME	Q' TY	MATERIAL/FINISH



深圳市华宇创精密电子有限公司

TOLERANCE:
X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15
X.' $\pm 2'$ X.X' $\pm 0.5'$ 

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :
吴迪DATE :
2012-02-11PART NAME:
TF+2SIM卡座三层卡座CHECKED BY:
马跃DATE :
2012-02-11PART NO. HYC01-3IN124-460
MOLD NO.APPROVED BY:
邱国夷DATE :
2012-02-11DRAW NO: HYC-SIM12021101
SHEET NO. 2 OF 2